8-bit Proprietary Microcontrollers

CMOS

F²MC-8FX MB95130M Series

MB95136M/F133MS/F133NS/F133JS/F134MS/F134NS/F134JS/ MB95F136MS/F136NS/F136JS/F133MW/F133NW/F133JW/F134MW/ MB95F134NW/F134JW/F136MW/F136NW/F136JW/FV100D-103

■ DESCRIPTION

The MB95130M series is general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions.

Note: F2MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- F2MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - Bit test branch instruction
 - Bit manipulation instructions etc.
- Clock
 - Main clock
 - Main PLL clock
 - Sub clock (for dual clock product)
 - Sub PLL clock (for dual clock product)

(Continued)

Be sure to refer to the "Check Sheet" for the latest cautions on development.

"Check Sheet" is seen at the following support page

URL: http://www.fujitsu.com/global/services/microelectronics/product/micom/support/index.html

"Check Sheet" lists the minimal requirement items to be checked to prevent problems beforehand in system development.



(Continued)

- Timer
 - 8/16-bit compound timer
 - 8/16-bit PPG
 - 16-bit PPG
 - Timebase timer
 - Watch prescaler (for dual clock product)
- LIN-UART
 - Full duplex double buffer
 - Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
- UART/SIO
 - Full duplex double buffer
 - Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
- External interrupt
 - Interrupt by edge detection (rising, falling, or both edges can be selected)
 - Can be used to recover from low-power consumption (standby) modes.
- 8/10-bit A/D converter
 - 8-bit or 10-bit resolution can be selected.
- Low-power consumption (standby) mode
 - Stop mode
 - Sleep mode
 - Watch mode (for dual clock product)
 - Timebase timer mode
- I/O port
 - The number of maximum ports
 - Single clock product : 20 ports
 - Dual clock product : 18 ports
 - Configuration
 - General-purpose I/O ports (COMS) : Single clock product : 20 ports

Dual clock product: 18 ports

• Programmable input voltage levels of port

Automotive input level / CMOS input level / hysteresis input level

• Flash memory security function

Protects the content of Flash memory (Flash memory device only)

■ MEMORY LINEUP

	Flash memory	RAM	
MB95F133MS/F133NS/F133JS	8 Kbytes	256 bytes	
MB95F133MW/F133NW/F133JW	o Royles	250 Dytes	
MB95F134MS/F134NS/F134JS	16 Khytoo	512 bytes	
MB95F134MW/F134NW/F134JW	16 Kbytes	512 bytes	
MB95F136MS/F136NS/F136JS	20 Khytaa	1 Khyto	
MB95F136MW/F136NW/F136JW	32 Kbytes	1 Kbyte	

■ PRODUCT LINEUP

Parameter Type ROM capacity*1 RAM capacity*1 Reset output	MB95136M MASK ROM product Selectable Single/Dual clock*3 Yes/No	MB95F134MS	MB95F134NS MB95F136NS		mB95F134NW mB95F136NW ory product	MB95F134JS MB95F136JS	MB95F134JW MB95F136JW			
Parameter Type ROM capacity*1 RAM capacity*1 Reset output Clock system	MASK ROM product Selectable Single/Dual clock*3 Yes/No	MB95F136MS Single	Yes clock	Flash memorals Kbytes (Max) Dual	pry product	MB95F136JS	MB95F136JW			
Type ROM capacity*1 RAM capacity*1 Reset output Clock system	Selectable Single/Dual clock*3		Yes clock	32 Kbytes (Max) 1 Kbyte (Max) Dual	x)					
ROM capacity*1 RAM capacity*1 Reset output Clock system	Selectable Single/Dual clock*3		Yes clock	32 Kbytes (Max) 1 Kbyte (Max) Dual	x)					
RAM capacity*1 Reset output Clock system	Single/Dual clock*3 Yes/No		Yes clock	1 Kbyte (Max) Dual						
Reset output Clock system	Single/Dual clock*3 Yes/No		clock	Dual						
Clock system	Single/Dual clock*3 Yes/No		clock		clock					
system	Single/Dual clock*3 Yes/No				clock	Single clock				
Low voltage detection		No	Yes				Dual clock			
Oreset				No	Yes/No No Yes No Yes					
Clock supervisor			No Yes							
I CPU functions [N	Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8, and 16 bits Minimum instruction execution time : 61.5 ns (at machine clock frequency 16.25 MHz) Interrupt processing time : 0.6 μs (at machine clock frequency 16.25 MHz)									
purpose I/O port	• Dual clock ¡ Programmab	Single clock product : 20 ports Dual clock product : 18 ports Programmable input voltage levels of port : Automotive input level / CMOS input level / hysteresis input level								
Timebase timer	Interrupt cycl	terrupt cycle: 0.5 ms, 2.1 ms, 8.2 ms, 32.8 ms (at main oscillation clock 4 MHz)								
timer	Reset generated cycle At main oscillation clock 10 MHz : Min 105 ms At sub oscillation clock 32.768 kHz (for dual clock product) : Min 250 ms									
Wild register (Capable of re	eplacing 3 byte	es of ROM dat	a						
R OIS/TRAU	Data transfer capable in UART/SIO Full duplex double buffer, Variable data length (5/6/7/8-bit), built-in baud rate generator NRZ type transfer format, error detected function LSB-first or MSB-first can be selected. Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable									
LIN-UART (Dedicated reload timer allowing a wide range of communication speeds to be set. Full duplex double buffer. Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable LIN functions available as the LIN master or LIN slave.									
8/10-bit A/D converter (8 channels)	8-bit or 10-bit resolution can be selected.									

(Continued)

\leftarrow	Dort rumber										
`	Part number		MB95F133MS	MB95F133NS	MB95F133MW	MB95F133NW	MB95F133JS	MB95F133JW			
		MB95136M	MB95F134MS	MB95F134NS	MB95F134MW MB95F136MW	MB95F134NW	MB95F134JS	MB95F134JW			
Pa	rameter		WID931 130WI3	MD931 130N3	IND931 130IVIV	WID931 130I4W	WID931 13003	WID931 1300W			
	compound timer	Built-in timer fu Count clock: 7	Each channel of the timer can be used as "8-bit timer x 2 channels" or "16-bit timer x 1 channel". Built-in timer function, PWC function, PWM function, capture function and square wave-form output Count clock: 7 internal clocks and external clock can be selected.								
16-bit PPG Counter operating clock: Eight selectable clock sources Support for external trigger start											
ons	8/16-bit PPG	Each channel of the PPG can be used as "8-bit PPG x 2 channels" or "16-bit PPG x 1 channel". Counter operating clock: Eight selectable clock sources									
Peripheral functions	(for dual	Counter valu		om 0 to 63. (0	ees (125 ms, 25 Capable of couluie to 60)			ecting clock			
Pe	clock product)	Four selectable interval times (125 ms, 250 ms, 500 ms, or 1 s)									
	External interrupt (8 channels)	Interrupt by edge detection (rising, falling, or both edges can be selected.) Can be used to recover from standby modes									
Flash memory		Write/Erase/I A flag indicat Number of w Data retentio Erase can be Block protect Flash Securi	Erase-Suspending completion rite/erase cyclen time: 20 years performed or ion with externity Feature for performed	d/Resume corn of the algorites (Minimum) ars neach block nal programmi protecting the	hm : 10000 times	Flash					
St	andby mode	Sleep, stop,	watch (for dua	l clock produc	t), and timebas	se timer					

^{*1 :} For ROM capacity and RAM capacity, refer to "1. Memory space" in "■ CPU CORE".

Note: Part number of evaluation product in MB95130M series is MB95FV100D-103. When using it, the MCU board (MB2146-303A) is required.

^{*2 :} For details of option, refer to "■ MASK OPTION".

^{*3 :} Specify clock mode when ordering MASK ROM.

^{*4 :} Embedded Algorithm is a trade mark of Advanced Micro Devices Inc.

■ OSCILLATION STABILIZATION WAIT TIME

The initial value of the main clock oscillation stabilization wait time is fixed to the maximum value. The maximum value is shown below.

Oscillation stabilization wait time	Remarks
(2 ¹⁴ -2) /Fcн	Approx. 4.10 ms (at main oscillation clock 4 MHz)

■ PACKAGES AND CORRESPONDING PRODUCTS

Part number Package	MB95136M	MB95F133MS/F133NS MB95F134MS/F134NS MB95F136MS/F136NS MB95F133JS MB95F134JS MB95F136JS	MB95F133MW/F133NW MB95F134MW/F134NW MB95F136MW/F136NW MB95F133JW MB95F134JW MB95F136JW
FPT-28P-M17	\circ	\circ	0
BGA-224P-M08	X	×	X

○ : Available× : Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON SELECTING PRODUCTS

Notes on using evaluation products

The Evaluation product has not only the functions of the MB95130M series but also those of other products to support software development for multiple series and models of the F²MC-8FX. The I/O addresses for peripheral resources not used by the MB95130M series are therefore access-barred. Read/write access to those access-barred addresses may cause peripheral resources supposed to be unused to operate, resulting in unexpected malfunctions of hardware or software.

Particularly, do not use word access to an odd-numbered-byte address in the prohibited areas (If such access is used, the address may be read or written unexpectedly).

Also, as the read values of prohibited addresses on the evaluation product are different to the values on the flash memory and mask ROM products, do not use these values in the program.

The Evaluation product does not support the functions of some bits in single-byte registers. Read/write access to these bits does not cause hardware malfunctions. The Evaluation, Flash memory, and MASK ROM products are designed to behave completely the same way in terms of hardware and software.

· Difference of memory spaces

If the amount of memory on the Evaluation product is different from that of the Flash memory or MASK ROM product, carefully check the difference in the amount of memory from the model to be actually used when developing software.

For details of memory space, refer to "■ CPU CORE".

Current consumption

- The current consumption of Flash memory product is greater than for MASK ROM product.
- For details of current consumption, refer to "■ ELECTRICAL CHARACTERISTICS".

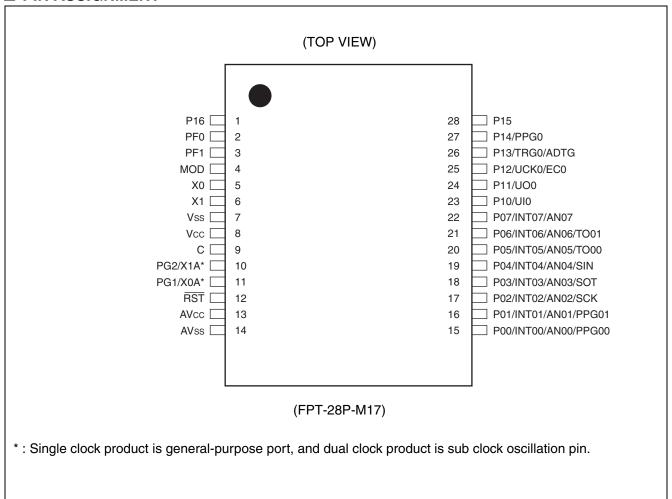
Package

For details of information on each package, refer to "■ PACKAGES AND CORRESPONDING PRODUCTS" and "■ PACKAGE DIMENSION".

Operating voltage

The operating voltage is different among the Evaluation, Flash memory, and MASK ROM products. For details of the operating voltage, refer to "■ ELECTRICAL CHARACTERISTICS".

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

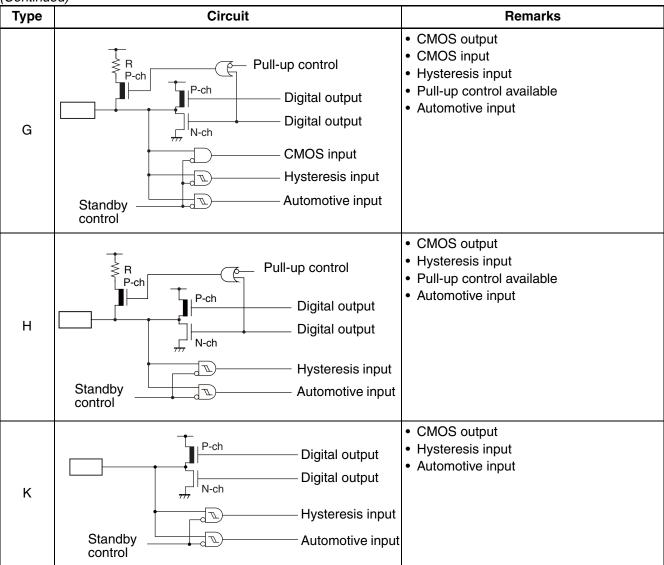
Pin no.	Pin name	I/O circuit type*	Function
1	P16	Н	General-purpose I/O port
2	PF0	I/	Canada numana I/O mant fau laura august
3	PF1	K	General-purpose I/O port for large current
4	MOD	В	Operating mode designation pin
5	X0	۸	Main clock oscillation input pin
6	X1	Α	Main clock oscillation input/output pin
7	Vss	_	Power supply pin (GND)
8	Vcc	_	Power supply pin
9	С		Capacity connection pin
10	PG2/X1A	H/A	Single clock product is general-purpose port (PG2) . Dual clock product is sub clock input/output oscillation pin (32 kHz) .
11	PG1/X0A	П/А	Single clock product is general-purpose port (PG1) . Dual clock product is sub clock input oscillation pin (32 kHz) .
12	RST	B'	Reset pin
13	AVcc	_	A/D converter power supply pin
14	AVss	_	A/D converter power supply pin (GND)
15	P00/INT00/ AN00/PPG00		General-purpose I/O port Shared with external interrupt input (INT00), A/D converter analog input (AN00) and 8/16-bit PPG ch.0 output (PPG00).
16	P01/INT01/ AN01/PPG01	5	General-purpose I/O port Shared with external interrupt input (INT01), A/D converter analog input (AN01) and 8/16-bit PPG ch.0 output (PPG01).
17	P02/INT02/ AN02/SCK	D	General-purpose I/O port Shared with external interrupt input (INT02), A/D converter analog input (AN02) and LIN-UART clock I/O (SCK).
18	P03/INT03/ AN03/SOT		General-purpose I/O port Shared with external interrupt input (INT03), A/D converter analog input (AN03) and LIN-UART data output (SOT).
19	P04/INT04/ AN04/SIN	E	General-purpose I/O port Shared with external interrupt input (INT04), A/D converter analog input (AN04) and LIN-UART data input (SIN).
20	P05/INT05/ AN05/TO00		General-purpose I/O port Shared with external interrupt input (INT05 & INT06), A/D converter
21	P06/INT06/ AN06/TO01	D	analog input (AN05 & AN06) and 8/16-bit compound timer ch.0 output (TO00 & TO01).
22	P07/INT07/ AN07		General-purpose I/O port Shared with external interrupt input (INT07) and A/D converter analog input (AN07).

Pin no.	Pin name	I/O circuit type*	Function
23	P10/UIO	G	General-purpose I/O port Shared with UART/SIO ch.0 data input (UI0)
24	P11/UO0		General-purpose I/O port Shared with UART/SIO ch.0 data output (UO0)
25	P12/UCK0/ EC0		General-purpose I/O port Shared with UART/SIO ch.0 clock I/O (UCK0) and 8/16-bit com- pound timer ch.0 clock input (EC0)
26	P13/TRG0/ ADTG	н	General-purpose I/O port Shared with 16-bit PPG ch.0 trigger input (TRG0) and A/D converter trigger input (ADTG)
27	P14/PPG0		General-purpose I/O port Shared with 16-bit PPG ch.0 output (PPG0)
28	P15		General-purpose I/O port

^{* :} For the I/O circuit type, refer to "■ I/O CIRCUIT TYPE".

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
А	X1 (X1A) Clock input X0 (X0A) Standby control	 Oscillation circuit High-speed side Feedback resistance: approx. 1 MΩ Low-speed side Feedback resistance: approx. 10 MΩ
В	Mode input	Only for input Hysteresis input only for MASK ROM product Pull-down resistor available only to MASK ROM product
B'	Reset input N-ch Reset output	 Hysteresis input only for MASK ROM product Reset output
D	Pull-up control Digital output Digital output Analog input A/D control Standby control External interrupt control	CMOS output Hysteresis input Analog input Pull-up control available Automotive input
E	Pull-up control P-ch Digital output Digital output N-ch CMOS input Hysteresis input A/D control Standby control External interrupt control	 CMOS output CMOS input Hysteresis input Analog input Pull-up control available Automotive input



■ HANDLING DEVICES

Preventing latch-up

Care must be taken to ensure that maximum voltage ratings are not exceeded when the devices are used. Latch-up may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- and high-withstand voltage pins or if voltage higher than the rating voltage is applied between Vcc pin and Vss pin.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements. Also, take care to prevent the analog power supply voltage (AVcc, AVR) and analog input voltage from exceeding the digital power supply voltage (Vcc) when the analog system power supply is turned on or off.

Stable supply voltage

Supply voltage should be stabilized.

A sudden change in power supply voltage may cause a malfunction even within the guaranteed operating range of the V_{CC} power supply voltage.

For stabilization, in principle, keep the variation in Vcc ripple (p-p value) in a commercial frequency range (50 / 60 Hz) not to exceed 10% of the standard Vcc value and suppress the voltage variation so that the transient variation rate does not exceed 0.1 V/ms during a momentary change such as when the power supply is switched.

Precautions for use of external clock

Even when an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from the sub clock mode or stop mode.

■ PIN CONNECTION

Treatment of unused pins

Leaving unused input pins unconnected can cause abnormal operation or latch-up, leading to permanent damage. Unused input pins should always be pulled up or down through resistance of at least 2 k Ω . Any unused input/output pins may be set to the output mode and left open, or set to the input mode and treated the same as unused input pins. If there is any unused output pin, make it open.

Treatment of power supply pins on A/D converter

Connect to be AVcc = Vcc and AVss = Vss even if the A/D converter is not in use.

Noise riding on the AV $_{\text{CC}}$ pin may cause accuracy degradation. So, connect approx. 0.1 μ F ceramic capacitor as a bypass capacitor between AV $_{\text{CC}}$ and AV $_{\text{SS}}$ pins in the vicinity of this device.

Power Supply Pins

In products with multiple $V_{\rm CC}$ or $V_{\rm SS}$ pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However, all the pins must be connected to external power supply and a ground line to lower the electro-magnetic emission level, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating. Moreover, connect the current supply source with the $V_{\rm CC}$ and $V_{\rm SS}$ pins of this device at the low impedance.

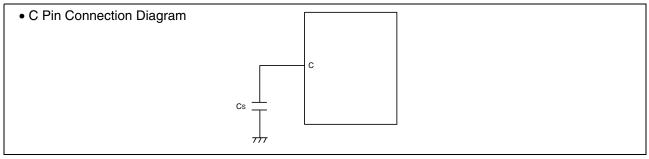
It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 μ F between V_{CC} and V_{SS} pins near this device.

Mode pin (MOD)

Connect the mode pin directly to Vcc or Vss pins.

To prevent the device unintentionally entering the test mode due to noise, lay out the printed circuit board so as to minimize the distance from the mode pins to Vcc or Vss pins and to provide a low-impedance connection.

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of $V_{\rm CC}$ pin must have a capacitance value higher than $C_{\rm S}$. For connection of smoothing capacitor $C_{\rm S}$, refer to the diagram below.



Analog power supply
 Always set the same potential to AVcc and Vcc. When Vcc > AVcc, the current may flow through the AN00 to
 AN07 pins.

■ PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER

Supported parallel programmers and adapters

The following table lists supported parallel programmers and adapters.

Package	Applicable adapter model	Parallel programmers
FPT-28P-M17	TEF110-95F136HSPF	AF9708(Ver 02.35G or greater) AF9709/B(Ver 02.35G or greater)

Note: For information about applicable adapter models and parallel programmers, contact the following: Flash Support Group, Inc. TEL: +81-53-428-8380

Sector configuration

The following table shows sector-specific addresses for data access by CPU and by the parallel programmer.

Flash memory	CPU address	Programmer address*
32 Kbytes	8000 _H	18000н
	FFFFH	1FFFF _H

^{*:} Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory.

Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 78000H to 7FFFFH.
- 3) Write data with the parallel programmer.

 MB95F134MS/F134NS/F134JS/F134MW/F134NW/F134JW (1 	16 Kby	rtes)
--	--------	-------

Flash memory	CPU address	Programmer address*
16 Kbytes	C000 _H	1C000 _H
	FFFF _H	1FFFF _H

Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 7C000H to 7FFFFH.
- 3) Write data with the parallel programmer.

These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

^{*:} Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory.

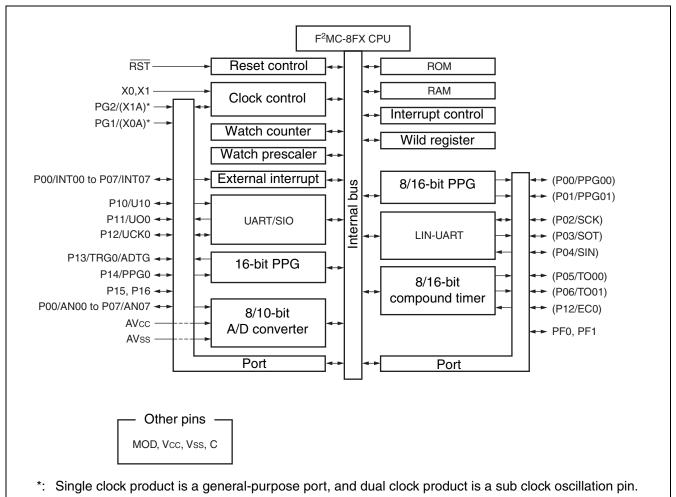
These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• MB95F133MS/F133NS/F133JS/F133MW/F133NW/F133JW (8 Kbytes)								
Flash memory	CPU address	Programmer address	*					
8 Kbytes	Е000н	1 <u>Е</u> 000н	_					
	<u>FFFF</u> +	<u>1FFFF</u> +	_					
*: Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory. These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.								

• Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 7E000_H to 7FFFF_H.
- 3) Write data with the parallel programmer.

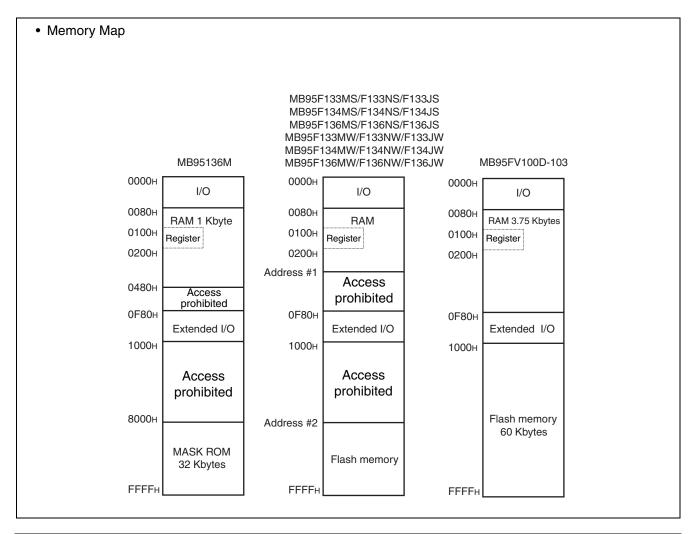
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

Memory space of the MB95130M series is 64 Kbytes and consists of I/O area, data area, and program area. The memory space includes special-purpose areas such as the general-purpose registers and vector table. Memory map of the MB95130M series is shown below.



	Flash memory	RAM	Address #1	Address #2	
MB95F133MS/F133NS/F133JS	8 Kbytes 256 bytes		0180н	Е000н	
MB95F133MW/F133NW/F133JW	o Rbytes	230 bytes	OTOOH	E000H	
MB95F134MS/F134NS/F134JS	16 Kbytes	512 bytes	0280н	С000н	
MB95F134MW/F134NW/F134JW	10 Kbytes	512 bytes	0200H	СОООН	
MB95F136MS/F136NS/F136JS	20 Khytoo	1 Khyto	0480н	8000 _H	
MB95F136MW/F136NW/F136JW	32 Kbytes	1 Kbyte	U460H	ОООО Н	

2. Register

The MB95130M series has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The dedicated registers are as include:

Program counter (PC) : A 16-bit register to indicate locations where instructions are stored.

Accumulator (A) : A 16-bit register for temporary storage of arithmetic operations. In the case of

an 8-bit data processing instruction, the lower 1-byte is used.

Temporary accumulator (T) : A 16-bit register which performs arithmetic operations with the accumulator.

In the case of an 8-bit data processing instruction, the lower 1-byte is used.

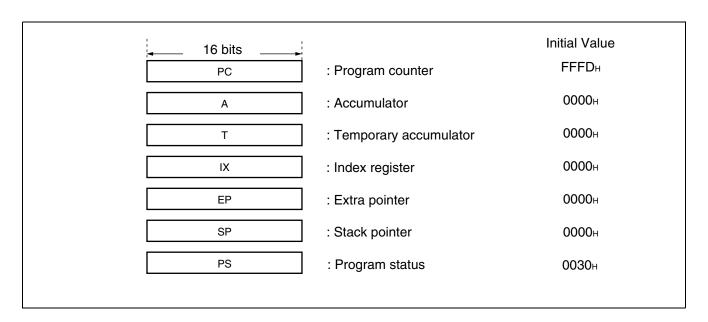
Index register (IX) : A 16-bit register for index modification

Extra pointer (EP) : A 16-bit pointer to point to a memory address.

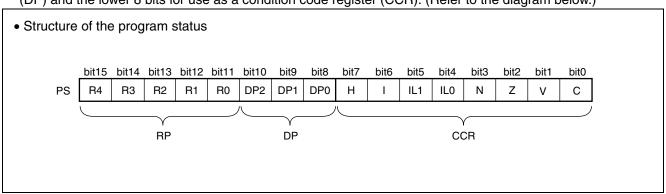
Stack pointer (SP) : A 16-bit register to indicate a stack area.

Program status (PS) : A 16-bit register for storing a register bank pointer, a direct bank pointer, and

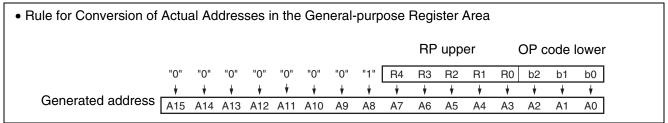
a condition code register



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and a direct bank pointer (DP) and the lower 8 bits for use as a condition code register (CCR). (Refer to the diagram below.)



The RP indicates the address of the register bank currently being used. The relationship between the content of RP and the real address conforms to the conversion rule illustrated below:



The DP specifies the area for mapping instructions (16 different types of instructions such as MOV A and dir) using direct addresses to 0080_H to 00FF_H.

Direct bank pointer (DP2 to DP0)	Specified address area	Mapping area
XXX _B (no effect to mapping)	0000н to 007Fн	0000н to 007Fн (without mapping)
000 _B (initial value)		0080н to 00FFн (without mapping)
001в		0100н to 017Fн
010в		0180н to 01FFн
011в	0080⊬ to 00FF⊬	0200н to 027Fн
100в	- 0000H tO 00FFH	0280н to 02FFн
101в		0300н to 037Fн
110в		0380н to 03FFн
111в		0400н to 047Fн

The CCR consists of the bits indicating arithmetic operation results or transfer data content and the bits that control CPU operations at interrupt.

H flag : Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation.

Cleared to "0" otherwise. This flag is for decimal adjustment instructions.

I flag : Interrupt is enabled when this flag is set to "1". Interrupt is disabled when this flag is set to "0".

The flag is cleared to "0" when reset.

IL1, IL0 : Indicates the level of the interrupt currently enabled. Processes an interrupt only if its request level is higher than the value indicated by these bits.

IL1	IL0	Interrupt level	Priority
0	0	0	High
0	1	1	†
1	0	2	<u> </u>
1	1	3	Low = no interruption

N flag : Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Cleared to "0" when the bit is set to "0".

Z flag : Set to "1" when an arithmetic operation results in "0". Cleared to "0" otherwise.

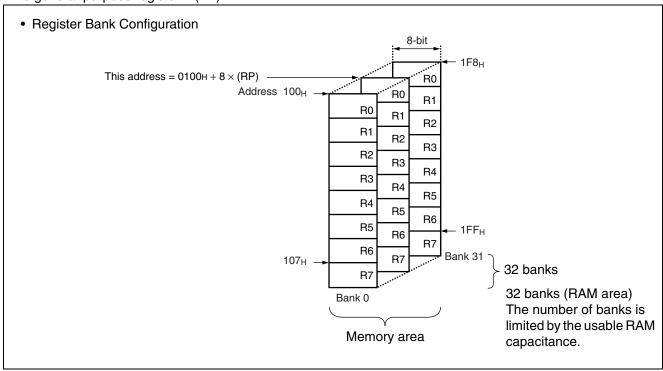
V flag : Set to "1" if the complement on 2 overflows as a result of an arithmetic operation. Cleared to "0" otherwise.

C flag : Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit data storage registers

The general-purpose registers are 8 bits and located in the register banks on the memory. 1-bank contains 8-registers. Up to a total of 32 banks can be used on the MB95130M series. The bank currently in use is specified by the register bank pointer (RP), and the lower 3 bits of OP code indicates the general-purpose register 0 (R0) to general-purpose register 7 (R7).



■ I/O MAP

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register		0000000в
0001н	DDR0	Port 0 direction register		0000000в
0002н	PDR1	Port 1 data register	R/W	0000000В
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н		(Disabled)		_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	111111111
0006н	PLLC	PLL control register	R/W	0000000В
0007н	SYCC	System clock control register	R/W	1010X011в
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R	XXXXXXXX
000Ан	TBTC	Timebase timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	0000000в
000Dн to 0027н	_	(Disabled)		_
0027н	PDRF	Port F data register		0000000
0029н	DDRF	Port F data register		0000000В
0029н	PDRG	Port G data register		00000000В
002Aн 002Bн	DDRG	Port G direction register	R/W R/W	0000000В
002Dн 002Сн	PUL0	Port 0 pull-up register	R/W	0000000В
002Он 002Dн	PUL1	Port 1 pull-up register	R/W	0000000В
002Eн to 0034н	_	(Disabled)		
0035н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit compound timer 01 control status register 1 ch.0	R/W	0000000в
0037н	T00CR1	8/16-bit compound timer 00 control status register 1 ch.0	R/W	0000000В
0038н, 0039н	_	(Disabled)		_
003Ан	PC01	8/16-bit PPG1 control register ch.0		0000000В
003Вн	PC00	8/16-bit PPG0 control register ch.0	R/W	0000000В
003Сн to 0041н	_	(Disabled)		_
0042н	PCNTH0	16-bit PPG control status register (Upper byte) ch.0	R/W	0000000В
0043н	PCNTL0	16-bit PPG control status register (Lower byte) ch.0	R/W	0000000в

Address	Register abbreviation	Register name	R/W	Initial value
0044н to 0047н	_	(Disabled)	_	_
0048н	EIC00	External interrupt circuit control register ch.0/ch.1	R/W	0000000В
0049н	EIC10	External interrupt circuit control register ch.2/ch.3	R/W	0000000B
004Ан	EIC20	External interrupt circuit control register ch.4/ch.5	R/W	0000000В
004Вн	EIC30	External interrupt circuit control register ch.6/ch.7	R/W	0000000В
004Сн to 004Fн	_	(Disabled)	_	_
0050н	SCR	LIN-UART serial control register	R/W	0000000В
0051н	SMR	LIN-UART serial mode register	R/W	0000000В
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0053н	RDR/TDR	LIN-UART reception/transmission data register	R/W	0000000В
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXB
0056н	SMC10	UART/SIO serial mode control register 1 ch.0		0000000В
0057н	SMC20	UART/SIO serial mode control register 2 ch.0	R/W	00100000в
0058н	SSR0	UART/SIO serial status register ch.0	R/W	0000001в
0059н	TDR0	UART/SIO serial output data register ch.0	R/W	0000000В
005Ан	RDR0	UART/SIO serial input data register ch.0		0000000В
005Вн to 006Вн	_	(Disabled)		_
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000В
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000В
006Ен	ADDH	8/10-bit A/D converter data register (Upper byte)	R/W	0000000В
006Fн	ADDL	8/10-bit A/D converter data register (Lower byte)	R/W	0000000В
0070н	WCSR	Watch counter status register	R/W	0000000В
0071н		(Disabled)		_
0072н	FSR	Flash memory status register	R/W	000Х0000в
0073н	SWRE0	Flash memory sector writing control register 0		0000000В
0074н	SWRE1	Flash memory sector writing control register 1		0000000В
0075н	_	(Disabled)	_	_
0076н	WREN	Wild register address compare enable register	R/W	0000000В
0077н	WROR	Wild register data test setting register	R/W	0000000В

Address	Register abbreviation	Register name	R/W	Initial value
0078н	_	(Register bank pointer (RP) Mirror of direct bank pointer (DP)	_	_
0079н	ILR0	Interrupt level setting register 0	R/W	111111111
007Ан	ILR1	Interrupt level setting register 1	R/W	111111111
007Вн	ILR2	Interrupt level setting register 2	R/W	111111111
007Сн	ILR3	Interrupt level setting register 3	R/W	111111111
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111В
007Ен	ILR5	Interrupt level setting register 5	R/W	111111111
007Fн	_	(Disabled)		_
0F80н	WRARH0	Wild register address setting register (Upper byte) ch.0	R/W	0000000В
0F81н	WRARL0	Wild register address setting register (Lower byte) ch.0	R/W	0000000В
0F82н	WRDR0	Wild register data setting register ch.0	R/W	0000000В
0F83н	WRARH1	Wild register address setting register (Upper byte) ch.1	R/W	0000000В
0F84н	WRARL1	Wild register address setting register (Lower byte) ch.1	R/W	0000000В
0F85н	WRDR1	Wild register data setting register ch.1	R/W	0000000В
0F86н	WRARH2	Wild register address setting register (Upper byte) ch.2	R/W	0000000В
0F87н	WRARL2	Wild register address setting register (Lower byte) ch.2	R/W	0000000В
0F88н	WRDR2	Wild register data setting register ch.2		0000000В
0F89н to 0F91н	_	(Disabled)		_
0F92н	T01CR0	8/16-bit compound timer 01 control status register 0 ch.0	R/W	0000000В
0F93н	T00CR0	8/16-bit compound timer 00 control status register 0 ch.0	R/W	0000000В
0F94н	T01DR	8/16-bit compound timer 01 data register ch.0	R/W	0000000В
0F95н	T00DR	8/16-bit compound timer 00 data register ch.0	R/W	0000000В
0F96н	TMCR0	8/16-bit compound timer 00/01 timer mode control register ch.0	R/W	00000000в
0F97н to 0F9Вн	_	(Disabled)		_
0F9Cн	PPS01	8/16-bit PPG1 cycle setting buffer register ch.0		11111111В
0F9Dн	PPS00	8/16-bit PPG0 cycle setting buffer register ch.0	R/W	111111111
0F9Ен	PDS01	8/16-bit PPG1 duty setting buffer register ch.0	R/W	111111111
0F9Fн	PDS00	8/16-bit PPG0 duty setting buffer register ch.0	R/W	11111111В
0FA0н to 0FA3н	_	(Disabled)	_	_

Address	Register abbreviation	Register name	R/W	Initial value
0FA4н	PPGS	8/16-bit PPG start register	R/W	0000000в
0FA5н	REVC	8/16-bit PPG output inversion register	R/W	0000000В
0FA6н to 0FA9н	_	(Disabled)	_	_
0ГААн	PDCRH0	16-bit PPG down counter register (Upper byte) ch.0	R	0000000В
0ҒАВн	PDCRL0	16-bit PPG down counter register (Lower byte) ch.0	R	0000000В
0FAСн	PCSRH0	16-bit PPG cycle setting buffer register (Upper byte) ch.0	R/W	111111111
0FADн	PCSRL0	16-bit PPG cycle setting buffer register (Lower byte) ch.0	R/W	111111111
0FAEн	PDUTH0	16-bit PPG duty setting buffer register (Upper byte) ch.0	R/W	111111111
0FAFн	PDUTL0	16-bit PPG duty setting buffer register (Lower byte) ch.0	R/W	111111111
0FB0н to 0FBBн	_	(Disabled)	_	_
0FBCн	BGR1	LIN-UART baud rate generator register 1	R/W	0000000В
0FBDн	BGR0	LIN-UART baud rate generator register 0	R/W	0000000В
0FВЕн	PSSR0	UART/SIO dedicated baud rate generator prescaler selection register ch.0	R/W	0000000в
0FBFн	BRSR0	UART/SIO dedicated baud rate generator baud rate setting register ch.0	R/W	0000000в
0FC0н to 0FC2н	_	(Disabled)		_
0FС3н	AIDRL	A/D input disable register (Lower byte)	R/W	0000000в
0FC4н to 0FE2н	_	(Disabled)	_	_
0FE3н	WCDR	Watch counter data register	R/W	00111111в
0FE4н to 0FE6н	_	(Disabled)	_	_
0FE7н	ILSR2	Input level select register 2 (option)	R/W	0000000В
0FE8н, 0FE9н	_	(Disabled)		_
0FEAн	CSVCR	Clock supervisor control register	R/W	00111100в
0FEBн to 0FEDн	_	(Disabled)		_
0FEEн	ILSR	Input level select register		0000000В
0FEFн	WICR	Interrupt pin control register	R/W	01000000в
0FF0н to 0FFFн	_	(Disabled)	_	_

• R/W access symbols

R/W : Readable / Writable

R : Read only W : Write only

• Initial value symbols

0 : The initial value of this bit is "0".1 : The initial value of this bit is "1".

X : The initial value of this bit is undefined.

Note: Do not write to the "(Disabled)". Reading the "(Disabled)" returns an undefined value.

■ INTERRUPT SOURCE TABLE

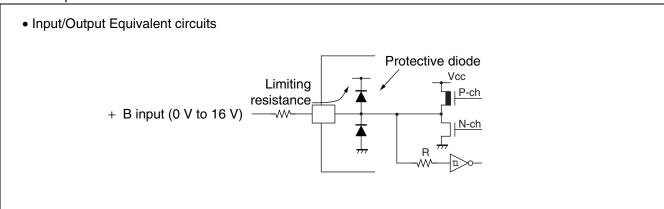
	Interrupt	Vector tab	le address	Bit name of	Same level	
Interrupt source	request number	Upper	Lower	interrupt level setting register	priority order (atsimultaneous occurrence)	
External interrupt ch.0	IRQ0	FFFA _H	FFFB⊦	L00 [1 : 0]	High	
External interrupt ch.4	INQU	ГГГАН	ГГГОН	L00 [1.0]	A	
External interrupt ch.1	IDO4	FFFO	FFF0	1.04.54 - 01	1 1	
External interrupt ch.5	IRQ1	FFF8 _H	FFF9 _H	L01 [1 : 0]		
External interrupt ch.2	IDOO	EEE0		1.00.14 . 01		
External interrupt ch.6	IRQ2	FFF6 _H	FFF7 _H	L02 [1 : 0]		
External interrupt ch.3	IDO	FFF4		1.00.14 . 01		
External interrupt ch.7	IRQ3	FFF4 _H	FFF5 _H	L03 [1 : 0]		
UART/SIO ch.0	IRQ4	FFF2 _H	FFF3 _H	L04 [1 : 0]		
8/16-bit compound timer ch.0 (Lower)	IRQ5	FFF0 _H	FFF1 _H	L05 [1:0]		
8/16-bit compound timer ch.0 (Higher)	IRQ6	FFEEH	FFEFH	L06 [1:0]		
LIN-UART (reception)	IRQ7	FFECH	FFEDH	L07 [1:0]		
LIN-UART (transmission)	IRQ8	FFEAH	FFEBH	L08 [1 : 0]		
(Unused)	IRQ9	FFE8 _H	FFE9 _H	L09 [1 : 0]		
(Unused)	IRQ10	FFE6⊦	FFE7 _H	L10 [1 : 0]		
(Unused)	IRQ11	FFE4 _H	FFE5 _H	L11 [1 : 0]		
8/16-bit PPG ch.0 (Upper)	IRQ12	FFE2 _H	FFE3 _H	L12 [1 : 0]		
8/16-bit PPG ch.0 (Lower)	IRQ13	FFE0 _H	FFE1 _H	L13 [1 : 0]		
(Unused)	IRQ14	FFDE _H	FFDF⊦	L14 [1 : 0]		
16-bit PPG ch.0	IRQ15	FFDC _H	FFDD⊦	L15 [1 : 0]		
(Unused)	IRQ16	FFDA⊦	FFDB _H	L16 [1 : 0]		
(Unused)	IRQ17	FFD8 _H	FFD9⊦	L17 [1 : 0]		
8/10-bit A/D converter	IRQ18	FFD6⊦	FFD7 _H	L18 [1 : 0]		
Timebase timer	IRQ19	FFD4 _H	FFD5 _H	L19 [1 : 0]		
Watch prescaler/Watch counter	IRQ20	FFD2 _H	FFD3 _H	L20 [1 : 0]]	
(Unused)	IRQ21	FFD0 _H	FFD1 _H	L21 [1 : 0]		
(Unused)	IRQ22	FFCEH	FFCF _H	L22 [1 : 0]	▼	
Flash memory	IRQ23	FFCCH	FFCDH	L23 [1 : 0]	Low	

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum ratings

Parameter	Symbol	Rating		Unit	Remarks		
Parameter	Syllibol	Min	Max	Ullit	nemarks		
Power supply voltage*1	Vcc AVcc	Vss - 0.3	Vss + 6.0	V	*2		
Input voltage*1	Vı	Vss - 0.3	Vss + 6.0	V	*3		
Output voltage*1	Vo	Vss - 0.3	Vss + 6.0	V	*3		
Maximum clamp current	CLAMP	- 2.0	+ 2.0	mA	Applicable to pins*4		
Total maximum clamp current	Σ l $ $ CLAMP $ $	_	20	mA	Applicable to pins*4		
"L" level maximum	lo _{L1}		15	mA	Other than PF0, PF1		
output current	lol2		15	IIIA	PF0, PF1		
"L" level average	lolav1		4	- mA	Other than PF0, PF1 Average output current = operating current × operating ratio (1 pin)		
current	lolav2		12	III/X	PF0, PF1 Average output current = operating current × operating ratio (1 pin)		
"L" level total maximum output current	ΣΙοι	_	100	mA			
"L" level total average output current	Σ lolav	_	50	mA	Total average output current = operating current × operating ratio (Total of pins)		
"H" level maximum	І он1		– 15	A	Other than PF0, PF1		
output current	І он2	_	– 15	- mA	PF0, PF1		
"H" level average	Iонаv1		- 4	- mA	Other than PF0, PF1 Average output current = operating current × operating ratio (1 pin)		
current	Iонаv2	_	- 8	IIIA	PF0, PF1 Average output current = operating current × operating ratio (1 pin)		
"H" level total maximum output current	ΣІон	_	- 100	mA			
"H" level total average output current	ΣΙοнαν	_	- 50	mA	Total average output current = operating current × operating ratio (Total number of pins)		
Power consumption	Pd	_	320	mW			
Operating temperature	TA	- 40	+ 85	°C			
Storage temperature	Tstg	- 55	+ 150	°C			

- *1: The parameter is based on $AV_{SS} = V_{SS} = 0.0 \text{ V}.$
- *2: Apply equal potential to AVcc and Vcc. AVR should not exceed AVcc + 0.3 V.
- *3: V_I and V_O should not exceed Vcc + 0.3 V. V_I must not exceed the rating voltage. However, if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.
- *4: Applicable pins: P10 to P15, PF0, PF1 (Inapplicable pins: PG1, PG2)
 - Use within recommended operating conditions.
 - Use at DC voltage (current).
 - +B signal is an input signal that exceeds Vcc voltage. The + B signal should always be applied a limiting resistance placed between the + B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the + B signal is applied the input current
 to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the Vcc pin, and this affects other devices.
 - Note that if the + B signal is inputted when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the + B input is applied during power-on, the power supply is provided from the pins and the
 resulting power supply voltage may not be sufficient to operate the power-on reset.
 - Care must be taken not to leave the + B input pin open.
 - Note that analog system input/output pins other than the A/D input pins (LCD drive pins, etc.) cannot accept
 +B signal input.
 - Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

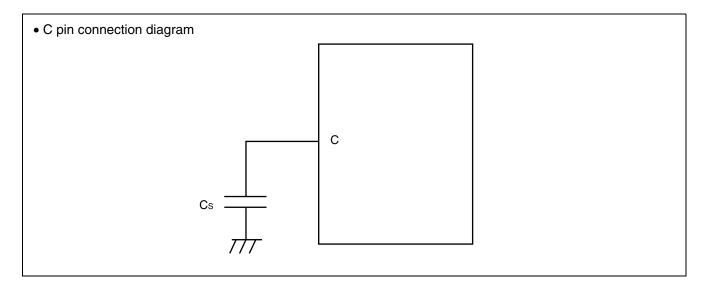
2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol Pin name		Condition	Value		Unit	Remarks
Parameter	Syllibol	Fili liallie	Condition	Min	Max	Ullit	nemarks
Power supply	Vcc,			2.42*2	5.5* ¹		At normal operation
	AVcc	_	_	2.3	5.5	V	Holds condition in stop mode
Smoothing capacitor	Cs	_	_	0.1	1.0	μF	*3
Operating temperature	Та	_	_	- 40	+ 85	°C	

^{*1:} The value varies depending on the operating frequency.

^{*3:} Use ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of Vcc pin must have a capacitance value higher than Cs. For connection of smoothing capacitor Cs, refer to the diagram below.



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

^{*2:} The value is 2.88 V when the low-voltage detection reset is used.

3. DC Characteristics

(Vcc = = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

					Value	= v ss = 0.0		Remarks	
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit		
"H" level input voltage	Vıнı	P04 (selectable in SIN), P10 (selectable in UI0)	_	0.7 Vcc	_	Vcc + 0.3	٧	Hysteresis input	
	Vihsi	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	0.8 Vcc	_	Vcc + 0.3	٧	Hysteresis input	
	VIHA	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	0.8 Vcc	_	Vcc + 0.3	٧	Pin input at selecting of Automotive input level	
	VIHM	RST, MOD	_	0.7 Vcc	_	Vcc + 0.3	٧	CMOS input (Flash memory product)	
			_	0.8 Vcc		Vcc + 0.3	٧	Hysteresis input (MASK ROM product)	
	VıL	P04 (selectable in SIN), P10 (selectable in UI0)	_	Vss - 0.3	_	0.3 Vcc	٧	Hysteresis input	
	VILS	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	Vss - 0.3	_	0.2 Vcc	٧	Hysteresis input	
"L" level input voltage	VILA	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	Vss - 0.3	_	0.5 Vcc	V	Pin input at selecting of Automotive input level	
	VILM	RST, MOD	_	Vss - 0.3	_	0.3 Vcc	V	CMOS input (Flash memory product)	
			_	Vss - 0.3	_	0.2 Vcc	V	Hysteresis input (MASK ROM product)	
"H" level output voltage	V _{OH1}	Output pin other than PF0, PF1	$I_{OH} = -4.0 \text{ mA}$	Vcc - 0.5	_	_	V		
	V _{OH2}	PF0, PF1	Iон = $-8.0 mA$	Vcc - 0.5			V		
"L" level output voltage	V _{OL1}	Output pin other than PF0 to PF7, RST*1	IoL = 4.0 mA	_	_	0.4	٧		
	V _{OL2}	PF0, PF1	IoL = 12 mA			0.4	٧		

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

Davamatav	0	D '	O a statistica sa		Value		1114	Remarks
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	
Input leakage current (Hi-Z out- put leakage current)	lu	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	0.0 V < V _I < V _{CC}	– 5	_	+ 5	μΑ	When the pull-up prohibition setting
Pull-up resistor	Rpull	P00 to P07, P10 to P16, PG1, PG2	V _I = 0.0 V	25	50	100	kΩ	When the pull-up permission setting
Pull-down resistor	Rмор	MOD	$V_{I} = V_{CC}$	50	100	200	kΩ	MASK ROM product only
Input capacity	Cin	Other than AVcc, AVss, C, Vcc and Vss	f = 1 MHz	_	5	15	pF	
		Vcc (External clock operation)	Vcc = 5.5 V FcH = 20 MHz FMP = 10 MHz Main clock mode (divided by 2)	_	9.5	12.5	mA	Flash memory product (at other than Flash memory writing and erasing)
				_	30	35	mA	Flash memory product (at Flash memory writing and erasing)
Power					7.2	9.5	mA	MASK ROM product
supply current*2	Icc		Fch = 32 MHz FMP = 16 MHz Main clock mode (divided by 2)	_	15.2	20.0	mA	Flash memory product (at other than Flash memory writing and erasing)
				_	35.7	42.5	mA	Flash memory product (at Flash memory writing and erasing)
					11.6	15.2	mA	MASK ROM product

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

D	Cumbal	Din rouse		-	Value	0.0 1, 1	11	Remarks
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	
Power supply current*2	Iccs		Vcc = 5.5 V FcH = 20 MHz FMP = 10 MHz Main Sleep mode (divided by 2)	_	4.5	7.5	mA	
			F _{CH} = 32 MHz F _{MP} = 16 MHz Main Sleep mode (divided by 2)	_	7.2	12.0	mA	
	IccL	Vcc (External clock operation)	Vcc = 5.5 V FcL = 32 kHz FMPL = 16 kHz Sub clock mode (divided by 2) , TA = +25 °C	_	45	100	μА	Dual clock product only
	Iccls		$V_{\text{CC}} = 5.5 \text{ V}$ $F_{\text{CL}} = 32 \text{ kHz}$ $F_{\text{MPL}} = 16 \text{ kHz}$ Sub sleep mode (divided by 2), $T_{\text{A}} = +25 ^{\circ}\text{C}$		10	81	μА	Dual clock product only
	Ісст		$V_{CC} = 5.5 \text{ V}$ $F_{CL} = 32 \text{ kHz}$ Watch mode Main stop mode $T_{A} = +25 \text{ °C}$	_	4.6	27	μА	Dual clock product only
	Iccmpll		Vcc = 5.5 V FcH = 4 MHz FMP = 10 MHz Main PLL mode (multiplied by 2.5)		9.3	12.5	mA	Flash memory product
				l	7	9.5	mA	MASK ROM product
			F _{CH} = 6.4 MHz F _{MP} = 16 MHz		14.9	20.0	mA	Flash memory product
			Main PLL mode (multiplied by 2.5)	_	11.2	15.2	mA	MASK ROM product
	Iccspll		$V_{\text{CC}} = 5.5 \text{ V}$ $F_{\text{CL}} = 32 \text{ kHz}$ $F_{\text{MPL}} = 128 \text{ kHz}$ $Sub \text{ PLL mode}$ $(\text{multiplied by 4}),$ $T_{\text{A}} = +25 \text{ °C}$	_	160	400	μА	Dual clock product only

(Continued)

(Vcc = AVcc = $5.0 \text{ V} \pm 10\%$, AVss = Vss = 0.0 V, Ta = $-40 \,^{\circ}\text{C}$ to $+85 \,^{\circ}\text{C}$)

Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
			Condition	Min	Тур	Max		
Power supply current*2	Істѕ	Vcc (External clock	$V_{CC} = 5.5 \text{ V}$ $F_{CH} = 10 \text{ MHz}$ $Timebase timer$ $mode$ $T_A = +25 ^{\circ}C$		0.15	1.1	mA	
	Іссн	operation)	$V_{CC} = 5.5 \text{ V}$ Sub stop mode $T_A = +25 \text{ °C}$		3.5	20.0	μΑ	Main stop mode for single clock product
	la		Vcc = 5.5 V FcH = 16 MHz When A/D conversion is in operation	_	2.4	4.7	mA	
	Іан	AV∞	Vcc = 5.5 V FcH = 16 MHz When A/D conversion is stopped TA = +25 °C	_	1	5	μΑ	

^{*1:} Product without clock supervisor only

- Refer to "4. AC Characteristics: (1) Clock Timing" for Fch and Fcl.
- Refer to "4. AC Characteristics: (2) Source Clock/Machine Clock" for FMP and FMPL.

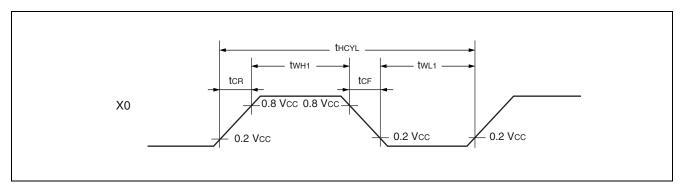
^{*2: •} The power supply current is specified by the external clock. When the low-voltage detection and clock supervisor options are selected, the consumption current values of both the low-voltage detection circuit (ILVD) and the built-in CR oscillator (Icsv) must also be added to the power supply current value.

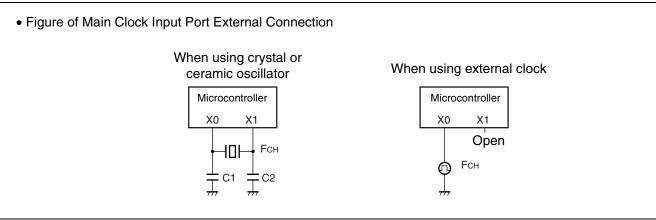
4. AC Characteristics

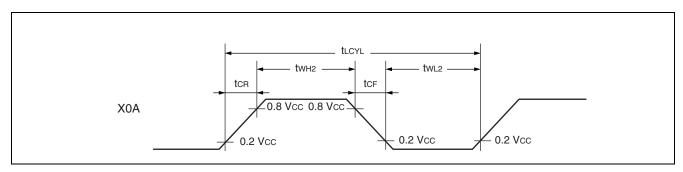
(1) Clock Timing

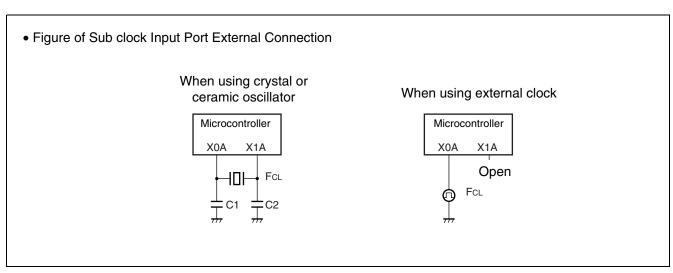
(Vcc = 2.42 V to 5.0 V, AVss = Vss = 0.0 V, T_A = $-40~^{\circ}C$ to $+85~^{\circ}C)$

Dovometer	Sym-	Din mass	Condi- tion	Value			l lm!#	Remarks	
Parameter	bol	Pin name		Min	Тур	Max	Unit	nemarks	
		X0, X1		1.00	_	16.25	MHz	When using main oscillation circuit	
	_			1.00		32.50	MHz	When using external clock	
	Fсн			3.00		10.00	MHz	Main PLL multiplied by 1	
Clock frequency				3.00		8.13	MHz	Main PLL multiplied by 2	
				3.00		6.50	MHz	Main PLL multiplied by 2.5	
	FcL	X0A, X1A			32.768		kHz	When using sub oscillation circuit	
					32.768	_	kHz	When using sub PLL Vcc = 2.3 V to 3.6 V	
	thcyl	X0, X1		61.5	_	1000	ns	When using main oscillation circuit	
Clock cycle time				30.8	_	1000	ns	When using external clock	
	tLCYL	X0A, X1A		_	30.5	_	μs	When using sub oscillation circuit	
lanut alaak aulaa width	twH1	X0		61.5	_	_	ns	When using external clock	
Input clock pulse width	twH2	X0A			15.2	_	μs	duty ratio is about 30% to 70%.	
Input clock rise/fall time	tcr tcr	X0, X0A		_	_	5	ns	When using external clock	







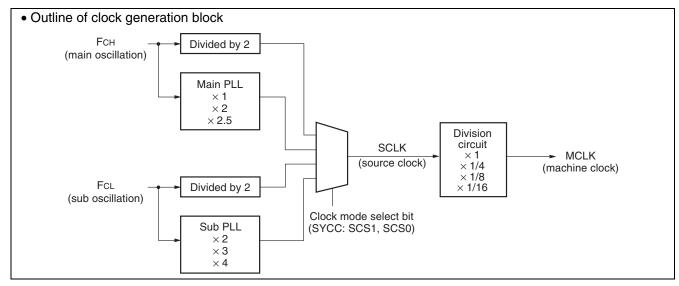


(2) Source Clock/Machine Clock

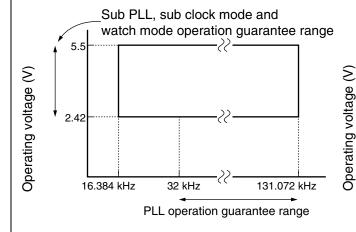
$$(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ Ta} = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

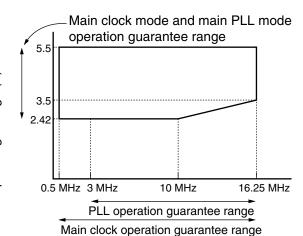
Parameter	Symbol	Pin		Value		Unit	Remarks
Farameter	Syllibol	name	Min	Тур	Max	Oilit	nemarks
Source clock cycle time*1	tsclk		61.5		2000	ns	When using main clock Min: F _{CH} = 16.25 MHz, PLL multiplied by 1 Max: F _{CH} = 1 MHz, divided by 2
(Clock before setting division)	ISOLK		7.6		61.0	μs	When using sub clock Min: FcL = 32 kHz, PLL multiplied by 4 Max: FcL = 32 kHz, divided by 2
Source clock	Fsp	_	0.50	_	16.25	MHz	When using main clock
frequency	FSPL	_	16.384	_	131.072	kHz	When using sub clock
Machine clock cycle time*2 (Minimum	tmclk		61.5	_	32000	ns	When using main clock Min: F _{SP} = 16.25 MHz, no division Max: F _{SP} = 0.5 MHz, divided by 16
instruction execution time)	UNICER		7.6		976.5	μs	When using sub clock Min: F _{SPL} = 131 kHz, no division Max: F _{SPL} = 16 kHz, divided by 16
Machine clock	F _{MP}		0.031	—	16.250	MHz	When using main clock
frequency	FMPL		1.024		131.072	kHz	When using sub clock

- *1: Clock before setting division due to machine clock division ratio selection bit (SYCC: DIV1 and DIV0). This source clock is divided by the machine clock division ratio selection bit (SYCC: DIV1 and DIV0), and it becomes the machine clock. Further, the source clock can be selected as follows.
 - Main clock divided by 2
 - PLL multiplication of main clock (select from 1, 2, 2.5 multiplication)
 - Sub clock divided by 2
 - PLL multiplication of sub clock (select from 2, 3, 4 multiplication)
- *2: Operation clock of the microcontroller. Machine clock can be selected as follows.
 - Source clock (no division)
 - Source clock divided by 4
 - Source clock divided by 8
 - Source clock divided by 16



- Operating voltage Operating frequency (When $T_A = -40 \,^{\circ}\text{C}$ to $+85 \,^{\circ}\text{C}$)
 - MB95F133MS/F133NS/F133JS/F134MS/F134NS/F134JS/F136MS/F136NS/F136JS/F133MW/F133NW/ MB95F133JW/F134MW/F134NW/F134JW/F136MW/F136NW/F136JW

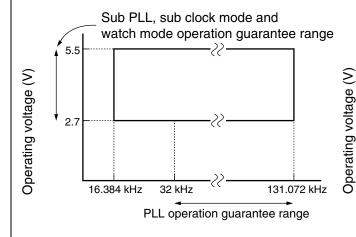




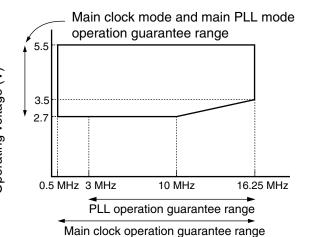
Source clock frequency (FSPL)

Source clock frequency (Fsp)

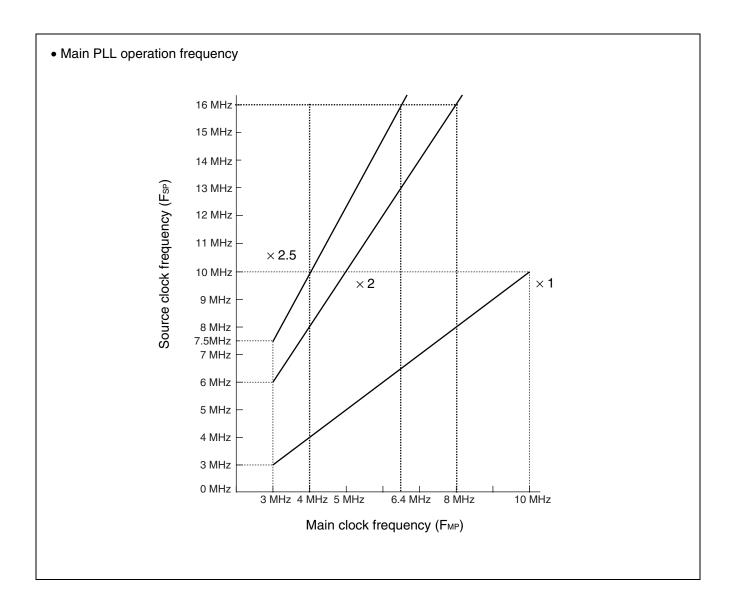
- \bullet Operating voltage Operating frequency (When $T_A = +5~^{\circ}C$ to $+35~^{\circ}C)$
 - MB95FV100D-103



Source clock frequency (FSPL)



Source clock frequency (Fsp)

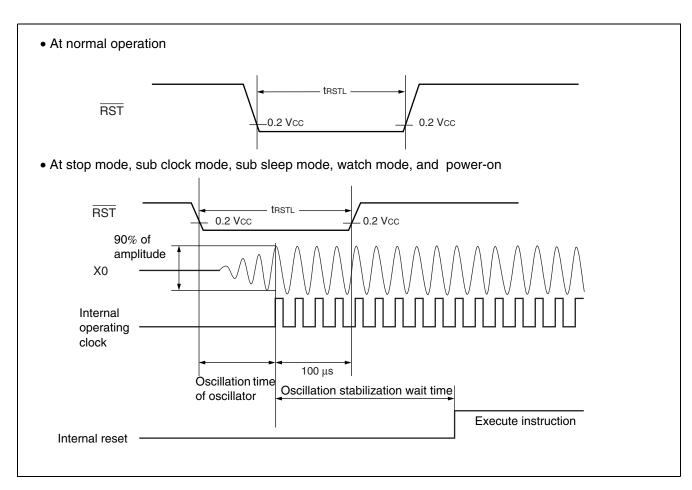


(3) External Reset

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ AV}_{SS} = \text{V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } +85 \,^{\circ}\text{C})$

Parameter	Symbol	Value			Remarks	
raiailletei	Syllibol	Min	Max	Unit	Hemarks	
		2 tмськ*1	_	ns	At normal operation	
RST "L" level pulse width	t RSTL	trestle Oscillation time of oscillator*2 + 100		μs	At stop mode, sub clock mode, sub sleep mode & watch mode	
		100		μs	At timebase timer mode	

- *1 : Refer to "(2) Source Clock/Machine Clock" for tmclk.
- *2 : Oscillation start time of oscillator is the time that the amplitude reaches 90 %. In the crystal oscillator, the oscillation time is between several ms and tens of ms. In ceramic oscillators, the oscillation time is between hundreds of μ s and several ms. In the external clock, the oscillation time is 0 ms.

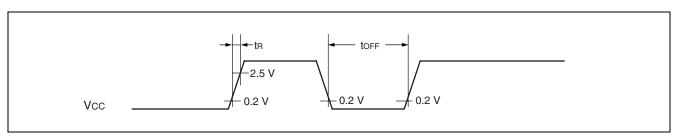


(4) Power-on Reset

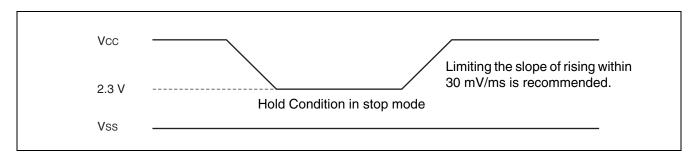
$$(AV_{SS} = V_{SS} = 0.0 \text{ V}, T_A = -40 \,^{\circ}\text{C to} + 85 \,^{\circ}\text{C})$$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Farameter	Syllibol	Condition	Min	Max	Oilit		
Power supply rising time	t⊓		_	50	ms		
Power supply cutoff time	toff	_	1		ms	Waiting time until power-on	

Note: Complete the power-on process within the selected oscillation stabilization wait time.



Note: Sudden change of power supply voltage may activate the power-on reset function. When changing power supply voltages during operation, set the slope of rising within 30 mV/ms as shown below.

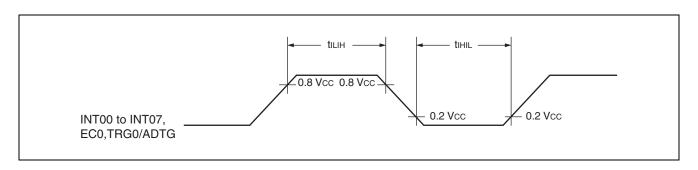


(5) Peripheral Input Timing

 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, TA = -40 °C to +85 °C)$

Parameter	Symbol	Pin name	Va	lue	Unit	Remarks	
raiailletei	Syllibol	riii iidiile	Min	Max	Oilit	nemarks	
Peripheral input "H" pulse	tılıн	INT00 to INT07,	2 t мськ*	_	ns		
Peripheral input "L" pulse	tıнıL	EC0, TRG0/ADTG	2 t мськ*		ns		

^{*:} Refer to "(2) Source Clock/Machine Clock" for tmclk.

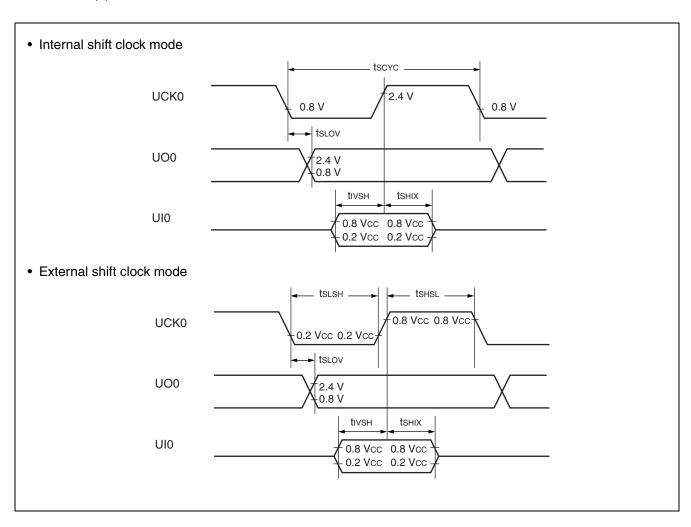


(6) UART/SIO Serial I/O Timing

 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, TA = -40 °C to +85 °C)$

Parameter	Symbol	Pin name	Condition	Val	ue	Unit	Remarks
raiametei	Symbol	Filitialile	Condition	Min	Max	Oilit	Hemarks
Serial clock cycle time	tscyc	UCK0, SCK		4 t мськ*	_	ns	
$UCK\downarrow \to UO$ time	tsLov	UCK0, UO0	Internal clock operation output pin :	- 190	+190	ns	
Valid UI → UCK ↑	tıvsн	UCK0, UI0	C _L = 80 pF + 1 TTL.	2 tмськ*	_	ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	tsнıx	UCK0, UI0		2 tмськ*	_	ns	
Serial clock "H" pulse width	t shsl	UCK0, SCK		4 tмськ*	_	ns	
Serial clock "L" pulse width	t slsh	UCK0, SCK	External clock	4 tмськ*	_	ns	
$UCK\downarrow \to UO$ time	tsLov	UCK0, UO0	operation output pin :	_	190	ns	
Valid UI → UCK ↑	tıvsн	UCK0, UI0	C∟ = 80 pF + 1 TTL.	2 tмськ*	_	ns	
UCK $\uparrow \rightarrow$ valid UI hold time	tsнıх	UCK0, UI0		2 tмськ*	_	ns	

^{*:} Refer to "(2) Source Clock/Machine Clock" for tmclk.



(7) LIN-UART Timing

Sampling at the rising edge of sampling clock*1 and prohibited serial clock delay*2 (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

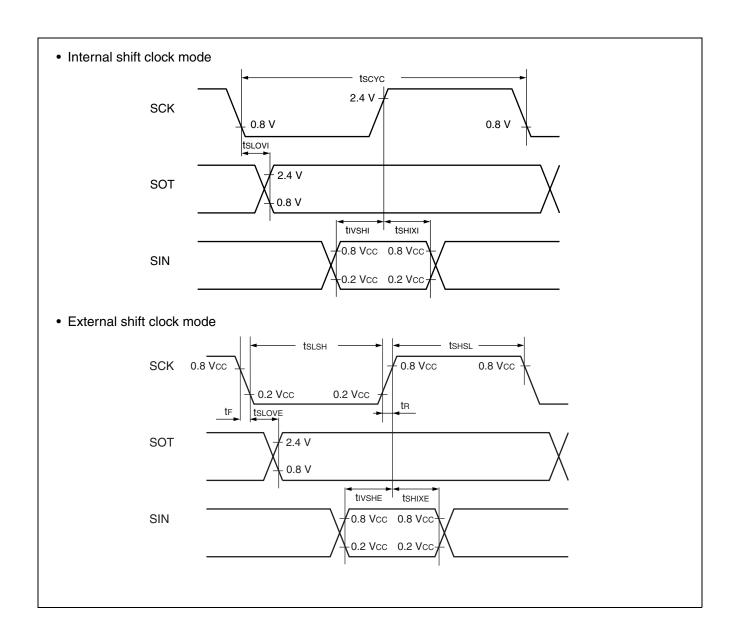
 $(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ Ta} = -40 \,^{\circ}\text{C to } +85 \,^{\circ}\text{C})$

Parameter	Sym-	Pin name	Condition	Va	lue	Unit
Parameter	bol	Pili liaille	Condition	Min	Max	Offic
Serial clock cycle time	tscyc	SCK		5 t мськ* ³		ns
$SCK \downarrow \to SOT$ delay time	tslovi	SCK, SOT	Internal clock operation output pin :	- 95	+95	ns
Valid SIN → SCK↑	tıvsнı	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*3 + 190		ns
$SCK \uparrow \rightarrow valid SIN hold time$	tshixi	SCK, SIN	·	0		ns
Serial clock "L" pulse width	tslsh	SCK		3 tмськ*3 — tв		ns
Serial clock "H" pulse width	tshsl	SCK		tмськ*3 + 95		ns
$SCK \downarrow \to SOT$ delay time	tslove	SCK, SOT	External clock		2 tмськ*3 + 95	ns
Valid SIN → SCK↑	tivshe	SCK, SIN	operation output pin:	190		ns
SCK↑→ valid SIN hold time	t shixe	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*3 + 95		ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	t⊓	SCK		_	10	ns

^{*1 :} Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

^{*2:} Serial clock delay function is used to delay half clock for the output signal of serial clock.

^{*3:} Refer to "(2) Source Clock/Machine Clock" for tmclk.



Sampling at the falling edge of sampling clock*1 and prohibited serial clock delay*2 (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

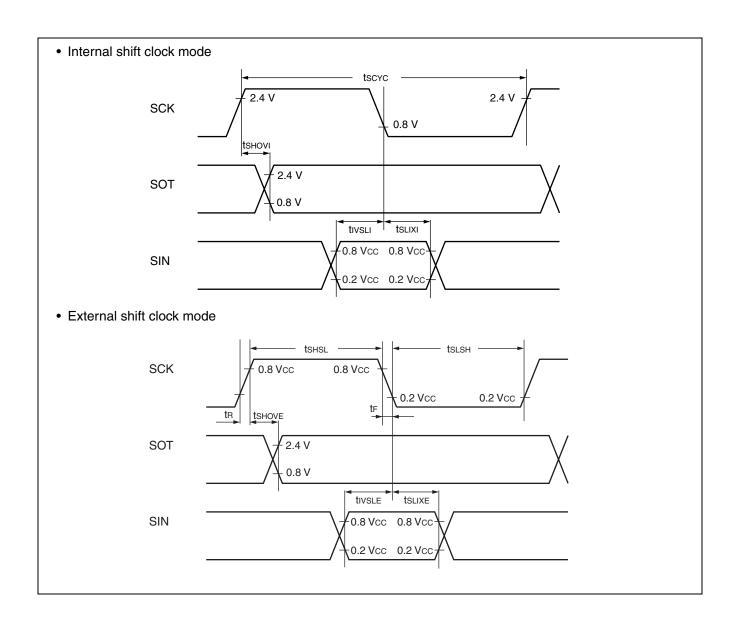
 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

Parameter	Sym-	Pin name	Condition	Va	lue	Unit
Farameter	bol		Condition	Min	Max	Ollit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
SCK↑→ SOT delay time	t shovi	SCK, SOT	Internal clock operation output pin :	- 95	+95	ns
Valid SIN $ ightarrow$ SCK \downarrow	t ıvslı	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*³ + 190	_	ns
$SCK \downarrow \to valid SIN hold time$	t slixi	SCK, SIN		0	_	ns
Serial clock "H" pulse width	tshsl	SCK		3 tмськ*3 — tr		ns
Serial clock "L" pulse width	t slsh	SCK		tмськ*³ + 95	_	ns
$SCK^{\uparrow} \to SOT$ delay time	t shove	SCK, SOT	External clock	_	2 tmclk*3 + 95	ns
Valid SIN → SCK \downarrow	tivsle	SCK, SIN	operation output pin :	190		ns
$SCK \downarrow \to valid SIN hold time$	tslixe	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*³ + 95	_	ns
SCK fall time	t₅	SCK		_	10	ns
SCK rise time	t⊓	SCK		_	10	ns

^{*1:} Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

^{*2:} Serial clock delay function is used to delay half clock for the output signal of serial clock.

^{*3:} Refer to "(2) Source Clock/Machine Clock" for tmclk.

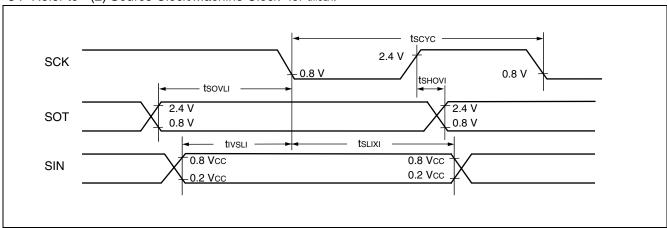


Sampling at the rising edge of sampling clock*1 and enabled serial clock delay*2 (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

Parameter	Sym-	Pin name	Condition	Valu	Unit	
Farameter	bol	Finitianie	Condition	Min	Max	Oilit
Serial clock cycle time	tscyc	SCK		5 t мськ*³	_	ns
SCK [↑] → SOT delay time	t shovi	SCK, SOT	Internal clock	- 95	+95	ns
Valid SIN → SCK \downarrow	tıvslı	SCK, SIN	operation output pin :	tмськ*3 + 190		ns
$SCK \downarrow \to valid SIN hold time$	t slixi	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	0		ns
$SOT \to SCK \downarrow delay\ time$	tsovu	SCK, SOT		_	4 tmclk*3	ns

- *1: Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.
- *2: Serial clock delay function is used to delay half clock for the output signal of serial clock.
- *3: Refer to "(2) Source Clock/Machine Clock" for tmclk.

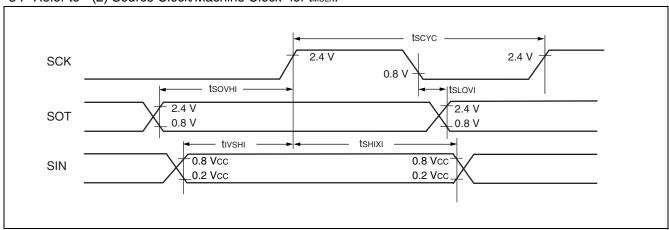


Sampling at the falling edge of sampling clock*1 and enabled serial clock delay*2 (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

Parameter	Sym-	Pin name	Condition	Valu	Unit	
Parameter	bol	Fill flaffie	Condition	Min	Max	Offic
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
$SCK \downarrow \to SOT$ delay time	tslovi	SCK, SOT	Internal clock	– 95	+95	ns
Valid SIN → SCK↑	tıvsнı	SCK, SIN	operating output pin :	tмськ*3 + 190	_	ns
$SCK \uparrow \rightarrow valid SIN hold time$	t shixi	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	0	_	ns
SOT → SCK↑ delay time	tsovні	SCK, SOT		_	4 tmclk*3	ns

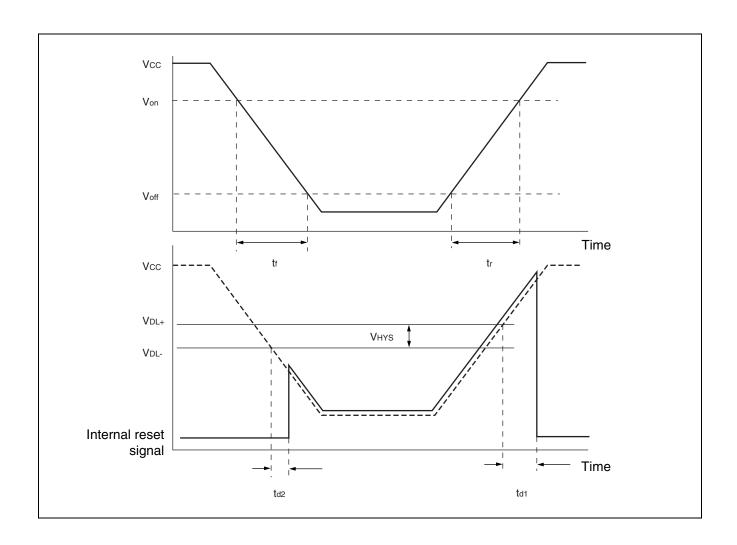
- *1: Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.
- *2: Serial clock delay function is used to delay half clock for the output signal of serial clock.
- *3: Refer to "(2) Source Clock/Machine Clock" for tmclk.



(8) Low voltage Detection

 $(AV_{SS} = V_{SS} = 0.0 \text{ V}, T_A = -40 \, ^{\circ}\text{C to } +85 \, ^{\circ}\text{C})$

			Value		(// 03			
Parameter	Sym-		1	1	Unit	Remarks		
	bol	Min	Тур	Max				
Release voltage	V_{DL+}	2.52	2.70	2.88	V	At power-supply rise		
Detection voltage	V _{DL} _	2.42	2.60	2.78	V	At power-supply fall		
Hysteresis width	V _{HYS}	70	100	_	mV			
Power-supply start voltage	Voff	_	_	2.3	V			
Power-supply end voltage	Von	4.9	_		V			
Power-supply voltage		0.3	_	_	μs	Slope of power supply that reset re- lease signal generates		
change time (at power supply rise)	tr	_	3000	_	μs	Slope of power supply that reset release signal generates within rating (V_{DL+})		
Power-supply voltage		300	_	_	μs	Slope of power supply that reset detection signal generates		
change time (at power supply fall)	tr	_	300	_	μs	Slope of power supply that reset detection signal generates within rating (V _{DL} -)		
Reset release delay time	t d1	—		400	μs			
Reset detection delay time	t d2	—		30	μs			
Consumption current	ILVD	_	38	50	μА	Consumption current of low voltage detection circuit only		



(9) Clock Supervisor Clock

(Vcc = AVcc = 5 V \pm 10%, AVss = Vss = 0.0 V, Ta = -40 °C to +85 °C)

Parameter	Sym-		Value		Unit	Remarks	
Parameter	bol	Min	Тур	Max	Ullit	nemarks	
Oscillation frequency	fоит	50	100	200	kHz		
Oscillation start time	twk	_	_	10	μs		
Current consumption	Icsv	_	20	36	μА	Current consumption of built-in CR oscillator at 100 kHz oscillation	

5. A/D Converter

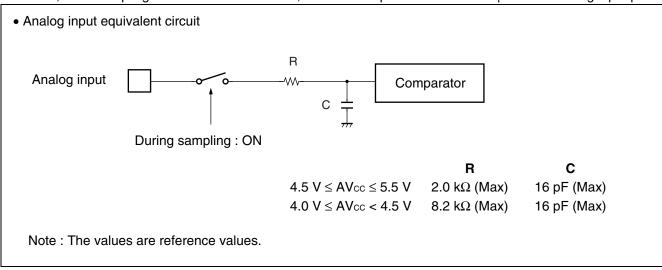
(1) A/D Converter Electrical Characteristics

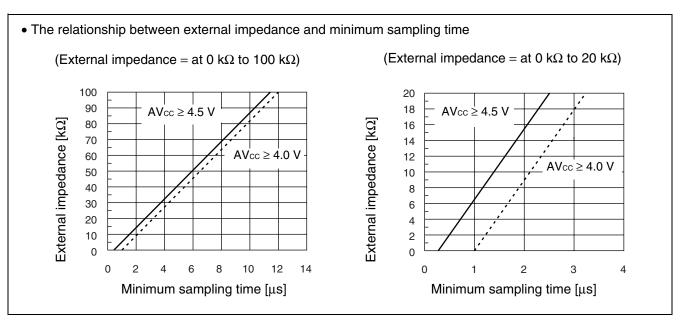
(AVcc = Vcc = 4.0 V to 5.5 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

Dorometer	Cumbal		Value		Hait	Domostko	
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Resolution		_		10	bit		
Total error		- 3.0		+ 3.0	LSB		
Linearity error		<u> </u>	- 2.5		+ 2.5	LSB	
Differential linear error		- 1.9	_	+ 1.9	LSB		
Zero transition voltage	Vот	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	٧		
Full-scale transition voltage	V _{FST}	AVcc – 4.5 LSB	AVcc – 1.5 LSB	AVcc + 0.5 LSB	٧		
Compare time		0.9		16500	μs	4.5 V ≤ AVcc ≤ 5.5 V	
Compare ume		1.8		16500	μs	4.0 V ≤ AVcc < 4.5 V	
Sampling time		0.6	_	8	μs	$4.5 \text{ V} \le \text{ AVcc} \le 5.5 \text{ V},$ At external impedance < at 5.4 k Ω	
Sampling time		1.2	_	∞	μs	$4.0 \text{ V} \le \text{AVcc} \le 4.5 \text{ V},$ At external impedance < at 2.4 k Ω	
Analog input current	lain	- 0.3	_	+ 0.3	μΑ		
Analog input voltage	Vain	AVss	_	AVcc	V		

(2) Notes on Using A/D Converter

- External impedance of analog input and its sampling time
 - A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting A/D conversion precision. Therefore to satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. Also, if the sampling time cannot be sufficient, connect a capacitor of about 0.1 µF to the analog input pin.





• Errors

As IAVcc - AVssI becomes smaller, values of relative errors grow larger.

(3) Definition of A/D Converter Terms

Resolution

The level of analog variation that can be distinguished by the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

• Linearity error (unit : LSB)

The deviation between the value along a straight line connecting the zero transition point ("00 0000 0000" $\leftarrow \rightarrow$ "00 0000 0001") of a device and the full-scale transition point

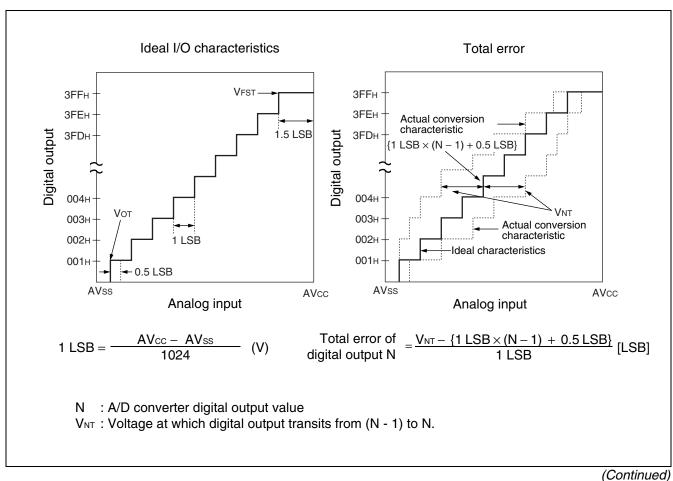
("11 1111 1111" \leftarrow \rightarrow "11 1111 1110") compared with the actual conversion values obtained.

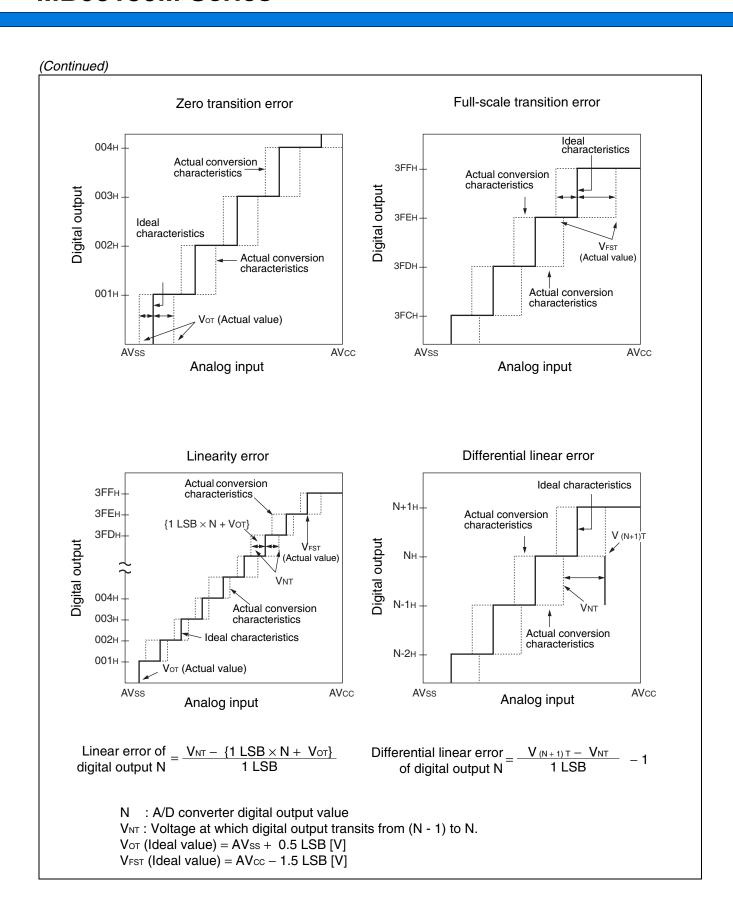
• Differential linear error (Unit : LSB)

Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.

Total error (unit: LSB)

Difference between actual and theoretical values, caused by a zero transition error, full-scale transition error, linearity error, quantum error, and noise.





6. Flash Memory Program/Erase Characteristics

Parameter	Value			Unit	Remarks	
Parameter	Min Typ Max		Max	Offic	nemarks	
Chip erase time		1.0*1	15.0*2	S	Excludes 00 _H programming prior erasure.	
Byte programming time	_	32	3600	μs	Excludes system-level overhead.	
Erase/program cycle	10000	_		cycle		
Power supply voltage at erase/ program	4.5		5.5	V		
Flash memory data retention time	20*3	_		year	Average T _A = +85 °C	

^{*1 :} $T_A = +25$ °C, $V_{CC} = 5.0$ V, 10000 cycles

^{*2 :} $T_A = +85 \, ^{\circ}C$, $V_{CC} = 4.5 \, V$, 10000 cycles

 $^{^*3}$: This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at +85 $^\circ$ C) .

■ MASK OPTION

No.	Part number	MB95136M	MB95F133MS/ F133NS/F133JS MB95F134MS/ F134NS/F134JS MB95F136MS/ F136NS/F136JS	MB95F133MW/ F133NW/F133JW MB95F134MW/ F134NW/F134JW MB95F136MW/ F136NW/F136JW	MB95FV100D-103
	Specifying procedure	Specify when ordering MASK	Setting disabled	Setting disabled	Setting disabled
	Clock mode select Single-system clock mode Dual-system clock mode	selectable	Single-system clock mode	Dual-system clock mode	Changing by the switch on MCU board
2	Low voltage detection reset* • With low voltage detection reset • Without low voltage detection reset	Specify when ordering MASK	Specified by part number	Specified by part number	Change by the switch on MCU board
	Clock supervisor* • With clock supervisor • Without clock supervisor	Specify when ordering MASK	Specified by part number	Specified by part number	Change by the switch on MCU board
4	Reset output* • With reset output • Without reset output	Specify when ordering MASK	Specified by part number	Specified by part number	MCU board switch set as following; • With supervisor: Without reset output • Without supervisor: With reset output
1 5	Oscillation stabilization wait time	stabilization	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /F _{CH}	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /F _{CH}	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /FcH

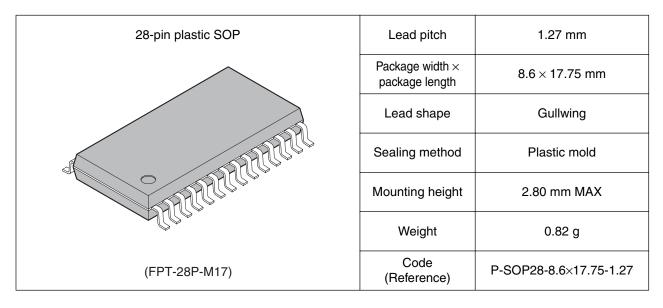
^{*:} Refer to table below about clock mode select, low voltage detection reset, clock supervisor select and reset output.

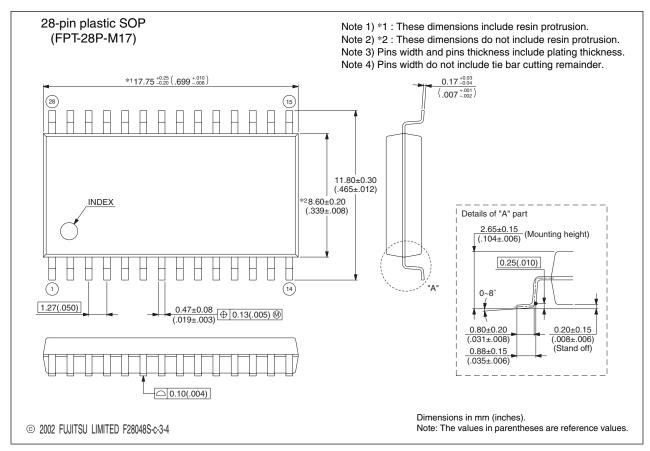
Part number	Clock mode select	Low-voltage detection reset	Clock supervisor	Reset output
MDOE400M	Single - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
MB95136M	Dual - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
MB95F133MS		No	No	Yes
MB95F133NS		Yes	No	Yes
MB95F133JS		Yes	Yes	No
MB95F134MS	Single - system	No	No	Yes
MB95F134NS		Yes	No	Yes
MB95F134JS		Yes	Yes	No
MB95F136MS		No	No	Yes
MB95F136NS		Yes	No	Yes
MB95F136JS		Yes	Yes	No
MB95F133MW		No	No	Yes
MB95F133NW		Yes	No	Yes
MB95F133JW		Yes	Yes	No
MB95F134MW		No	No	Yes
MB95F134NW	Dual - system	Yes	No	Yes
MB95F134JW		Yes	Yes	No
MB95F136MW		No	No	Yes
MB95F136NW		Yes	No	Yes
MB95F136JW		Yes	Yes	No
	Single - system	No	No	Yes
		Yes	No	Yes
MDOFFILL COD 155		Yes	Yes	No
MB95FV100D-103	Dual - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No

■ ORDERING INFORMATION

Part number	Package
MB95136MPFV MB95F133MSPFV MB95F133JSPFV MB95F134MSPFV MB95F134MSPFV MB95F134NSPFV MB95F136MSPFV MB95F136MSPFV MB95F136JSPFV MB95F133MWPFV MB95F133JWPFV MB95F133JWPFV MB95F134MWPFV MB95F134MWPFV MB95F134MWPFV MB95F136JWPFV MB95F136MWPFV MB95F136MWPFV MB95F136MWPFV MB95F136MWPFV MB95F136MWPFV MB95F136JWPFV	28-pin plastic SOP (FPT-28P-M17)
MB2146-303A (MB95FV100D-103PBT)	MCU board (224-pin plastic PFBGA (BGA-224P-M08)

■ PACKAGE DIMENSION





Please confirm the latest Package dimension by following URL. http://edevice.fujitsu.com/fj/DATASHEET/ef-ovpklv.html

■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results	
_	_	Preliminary Data Sheet → Data Sheet	
_	_	Added the part numbers. (MB95F133JS/MB95F133JW MB95F134JS/MB95F134JW MB95F136JS/MB95F136JW)	
4	■ PRODUCT LINEUP	Added the description "Clock supervisor" in the section "Option".	
15	■ PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER	Inserted "● Programming Method".	
25	■ I/O MAP	Added the address 0FEA _H .	
30		"Verified the Min value in the section of "Other than MB95FV100D-103", "In normal operating" of "Power supply voltage"; $2.5 \rightarrow 2.42$.	
	2. Recommended Operating Conditions	Verified the value in *2; 2.9 V \rightarrow 2.88 V.	
		Moved "H" level input voltage and "L" level input voltage to the section "3. DC Characteristics".	
31		Added the pin name at the "Pin name" in the section of V _{IHA} , "H" level input voltage.	
	3. DC Characteristics	Added the pin name at the "Pin name" in the section of V _{ILA} , "L" level input voltage.	
34		Deleted the line of "Fch = 16 MHz" in the section "Icts" of Power supply current.	
	4. AC Characteristics	Changed in the table; $Vcc = 2.5 \text{ V to } 5.5 \text{ V} \rightarrow Vcc = 2.42 \text{ V to } 5.5 \text{ V}.$	
35	(1) Clock Timing	Changed the Max value on the third column of the clock frequency; $16.25 \rightarrow 10.00$	
38	AC Characteristics (2) Source Clock/Machine Clock	Verified the diagram of Main PLL operation frequency range.	
50	(8) Low Voltage Detection	Changed the release voltage: $2.55 \rightarrow 2.52$ (Min value) $2.85 \rightarrow 2.88$ (Max value)	
	(o) 20W Voltage Detection	Changed the detection voltage: $2.45 \rightarrow 2.42$ (Min value) $2.75 \rightarrow 2.78$ (Max value)	

The information for microcontroller supports is shown in the following homepage. http://www.fujitsu.com/global/services/microelectronics/product/micom/support/index.html

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